

# Product Data Sheet

PD-0071-A

**3M™ Pak 50 Board-to-Board  
Connectors, P50 Series Socket  
and Plug**

**P5X-XXXSX-SX1-XX**

**P5X-XXXSX-RX1-XX**

**P5X-XXXPX-SX1-XX**

**P5X-XXXPX-RX1-XX**

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## 1.0 Scope

This data sheet summarizes test methods, test conditions and product performance for the 3M P50 Series Board-to-Board Connectors. The connectors are for Board-to-Board connection with two rows of ribbon style contacts at a 0.050" pitch. Connectors are available in straight, right angle, through hole, and SMT configurations.

## 2.0 Product Tested

Product:	P50 Socket
Product Number:	Group A – G1,G3: P50-100S-S1-EA G3: P50-060S-S1-EA G4: P50-060~080S-S1-EA I, II, IV: Contact Only III, V: P50-100S-RR1-EA
Related Specification Sheet:	TS-2046, TS-2047, TS-2052, TS-2051
Mating Product:	P50L Plug
Mating Product Number:	Group A – G1,G3: P50-100P-S1-EA G3: P50-060P-S1-EA G4: P50-060~080P-S1-EA I, II, IV: Contact Only II, V: P50-100P-RR1-EA

## 3.0 General Conditions

### 3.1 Test Specimens

The test specimens shall be strictly in compliance with the design, construction details and physical properties detailed in the relevant Technical Specification Sheet or Engineering Drawing.

#### 4.0 Test Results Summary

	Items	Specification	Test Method	Results
<b>General</b>	Visual and Construction	Conform to the design drawings	Visual Inspection	Pass
<b>Electrical</b>	Low Level Contact Resistance (LLCR)	Max. R: < 25 mΩ	4 Wire Measurement Current: 100mA DC	Pass
	Dielectric Withstanding Voltage (DWV)	No dielectric break down or Arcing	Apply 650 VAC <sub>RMS</sub> Voltage for 1 minute between 2 adjacent contacts	Pass
	Insulation Resistance (IR)	1000MΩ Min	Apply 500V DC for 1 minute between two adjacent contacts	Pass
	Current Rating: All Contacts in Series	Temperature Rise: 40°C or less Results: 0.5A = 13°C Temp. Rise 0.8A = 23°C Temp Rise 0.9A = 32°C Temp Rise 1.0A = 40°C Temp Rise	Ambient: 22°C	Pass
	Current Rating: 5 Contacts in Series	Temperature Rise: 40°C or less Results: 1.0A = 8°C Temp. Rise 1.5A = 11°C Temp Rise 1.8A = 29°C Temp Rise 2.0A = 38°C Temp Rise	Ambient: 22°C	Pass
	Current Rating: 1 Contacts	Temperature Rise: 40°C or less Results: 1.0A = 4°C Temp. Rise 1.5A = 10°C Temp Rise 2.0A = 15°C Temp Rise	Ambient: 22°C	Pass
<b>Environmenta I</b>	Humidity (Steady State)	No damage or deformation DWV: No Breakdown or Arcing LLCR: 25 mΩ Max	Humidity: 90~95% RH Temperature: 40°C Duration: 96 hours	Pass
	Life at Elevated Ambient Temperature (Thermal Aging)	LLCR: 40 mΩ Max No damage or deformation	Temperature: +85°C Duration: 240 hours	Pass
	Thermal Shock	No damage or deformation LLCR: 25 mΩ Max (5 Cycles, -55°C to +85°C)	1. -55°C 30 min 2. +25°C 5 min 3. +85°C 30 min 4. +25°C 5 min Repeat 1 - 4 for 5 Cycles	Pass
	Salt Spray	No serious corrosion LLCR: 25 mΩ Max	Temperature: 35°C Concentration: 5% Duration: 48 hrs	Pass
	H <sub>2</sub> S Exposure	No serious corrosion LLCR: 25 mΩ Max	Temperature: 40°C Concentration: 3 ppm RH: 80% Duration: 48 hrs	Pass
	SO <sub>2</sub> Exposure	No serious corrosion LLCR: 25 mΩ Max	Concentration: 10ppm Temperature: 40°C RH: 80% Duration: 48 hrs	Pass

<b>Mechanical</b>	Total Insertion Force	Insertion Force: <93.1N (100pins) < 0.931 N per contact	Measure with mating connectors	Pass
	Withdrawl Forces (Contact Retention Force)	Withdrawl Force: >19.6N(100pins) >19.6N per contact	Measure with mating connectors	Pass
	Durability (100 times)	No damage or deformation LLCR: Max. R: < 25mΩ	100 insertion/withdrawl cycles at 400-600 cycles/hour	Pass
	Durability (500 times)	No damage or deformation LLCR: Max. R: < 25 mΩ	500 insertion/withdrawl cycles at 1000 cycles/hour	Pass
	Vibration	No damage or deformation No electrical discontinuity > 1 μ sec	Frequency: 10~55Hz Amplitude: 1.52 mm Sweep time: 1 min  2 hours each in X, Y, and Z directions with 100mA DC applied to all contacts in series	Pass
	Mechanical Shock	No damage or deformation No electrical discontinuity > 1 μ sec	Acceleration: 490m/s <sup>2</sup> Shock Mode: half sin wave Duration: 11ms 3 Times each in X, Y, and Z and opposite directions with 100mA DC applied to all contacts in series	Pass
	Solderability (Wetting Time)	Zero cross time, 3s Max	1) Precondition: 85°C, 65%RH, 168h 2) Dip into solder bath, 2 mm depth, 20 mm/min. Eutectic: 235°C, Lead Free 245°C	Pass
	Solderability (Wetted Area)	95% minimum solder coverage	1) Precondition: 85°C, 65%RH, 168h 2) Dip into solder bath, 2 mm depth, 20 mm/min. Eutectic: 235°C, Lead Free 245°C	Pass
	Solder Heat Resistance	No physical abnormalities after test. LLCR: Max. R: < 25 mΩ	J-STD-020C, 260°C	Pass
	Solder Joint Reliability	Change in pull strength 50% maximum	1) Precondition: 85°C, 65%RH, 168h 2) Reflow solder 3 sec: Eutectic: 235°C, Lead Free 245°C 3) Temperature Cycle -40°C to +125°C, 30 min each extreme, 1000 cycles 4) Apply load at 5 mm/min on initial and after cycling	Pass
Whisker Test	No whiskers on Sn surface using 100x magnification	1) 60°C, 93% RH, 1000h 2) Ambient, 60 days	Pass	

## Testing

Test methods are based upon common electronics industry test methods.

### 5.1 Test Sequence

Tests conducted according to the sequence outlined in the chart below.

Tests	Sequence Group							
	A	B	C	D	E	F	G	Others*
Visual and Construction	1	1	1	1	1	1		
Insulation Resistance	2	2						
Dielectric Withstanding Voltage	3	3,7						
Low Level Contact Resistance	4	4,8	3,6	3,5	3,5	3,5		
Total Insertion Force	5							
Total Withdrawl Force	6							
Thermal Shock	7							
Vibration	8							
Shock	9		4					
Humidity		5	5					
Durability (100 times)		6	2	2	2	2		
Salt Spray		7						
SO2 Exposure				4				
H2S Exposure					4			
Life at Elevated Ambient Temperature						4		
Contact Retention Force							1	
Durability (500 Times)							2	
Current Rating							3	
Total Insertion and Withdrawl Force							4	
Solderability (Wetting time)								I
Solderability (Wetting area)								II
Soldering Heat Resistance								III
Solder Joint Reliability								IV
Whisker Test								V

\* Tests run individually

### Important Notice

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